

IN THE SPECIFICATION

Please replace the Abstract beginning on page 16, line 2, with the following:

ABSTRACT

~~An apparatus for bonding a chip has means for providing a substrate including a first chip. The apparatus further~~ In an embodiment of the invention an apparatus is configured to stack a plurality of semiconductor chips having the same or similar size. The apparatus includes a tape providing unit for providing an insulating adhesive tape, a tape attaching device for attaching the insulating adhesive tape to an area between [[the]]electrode pads of [[the]]a first chip, and a chip attaching device for attaching a second chip to the insulating adhesive tape.